

# PBSS5260PAP

60 V, 2 A PNP/PNP low V<sub>CEsat</sub> (BISS) transistor

12 December 2012

Product data sheet

## 1. General description

PNP/PNP low V<sub>CEsat</sub> Breakthrough In Small Signal (BISS) transistor in a leadless medium power DFN2020-6 (SOT1118) Surface-Mounted Device (SMD) plastic package.

NPN/PNP complement: PBSS4260PANP. NPN/NPN complement: PBSS4260PAN.

## 2. Features and benefits

- Very low collector-emitter saturation voltage V<sub>CEsat</sub>
- High collector current capability I<sub>C</sub> and I<sub>CM</sub>
- High collector current gain h<sub>FE</sub> at high I<sub>C</sub>
- Reduced Printed-Circuit Board (PCB) requirements
- High efficiency due to less heat generation
- AEC-Q101 qualified

## 3. Applications

- Load switch
- Battery-driven devices
- Power management
- Charging circuits
- Power switches (e.g. motors, fans)

## 4. Quick reference data

Table 1. Quick reference data

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
<b>Per transistor</b>							
V <sub>CEO</sub>	collector-emitter voltage	open base		-	-	-60	V
I <sub>C</sub>	collector current			-	-	-2	A
I <sub>CM</sub>	peak collector current	single pulse; t <sub>p</sub> ≤ 1 ms		-	-	-3	A
<b>Per transistor</b>							
R <sub>CEsat</sub>	collector-emitter saturation resistance	I <sub>C</sub> = -1 A; I <sub>B</sub> = -100 mA; pulsed; t <sub>p</sub> ≤ 300 µs; δ ≤ 0.02 ; T <sub>amb</sub> = 25 °C		-	-	250	mΩ



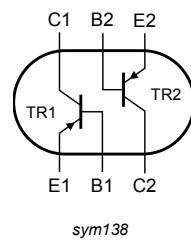
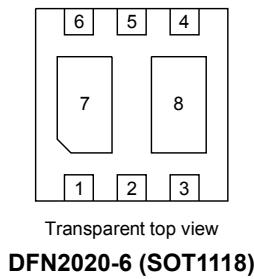
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## 5. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	E1	emitter TR1		
2	B1	base TR1		
3	C2	collector TR2		
4	E2	emitter TR2		
5	B2	base TR2		
6	C1	collector TR1		
7	C1	collector TR1		
8	C2	collector TR2		



## 6. Ordering information

Table 3. Ordering information

Type number	Package		
	Name	Description	Version
PBSS5260PAP	DFN2020-6	plastic thermal enhanced ultra thin small outline package; no leads; 6 terminals; body 2 x 2 x 0.65 mm	SOT1118

## 7. Marking

Table 4. Marking codes

Type number	Marking code
PBSS5260PAP	2P

## 8. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

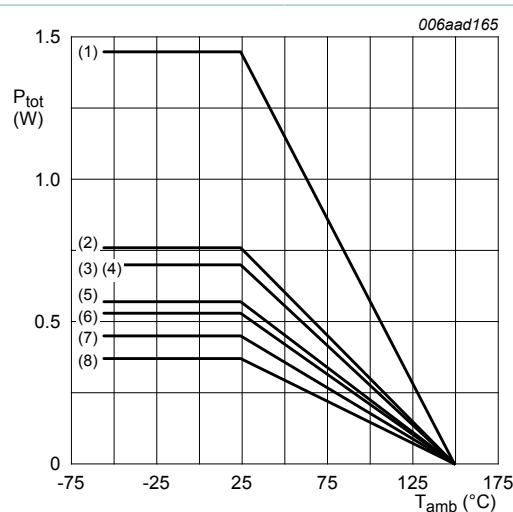
Symbol	Parameter	Conditions		Min	Max	Unit
<b>Per transistor</b>						
$V_{CBO}$	collector-base voltage	open emitter		-	-60	V
$V_{CEO}$	collector-emitter voltage	open base		-	-60	V
$V_{EBO}$	emitter-base voltage	open collector		-	-7	V
$I_C$	collector current			-	-2	A
$I_{CM}$	peak collector current	single pulse; $t_p \leq 1$ ms		-	-3	A
$I_B$	base current			-	-0.3	A

Symbol	Parameter	Conditions		Min	Max	Unit
$I_{BM}$	peak base current	single pulse; $t_p \leq 1 \text{ ms}$		-	-1	A
$P_{tot}$	total power dissipation	$T_{amb} \leq 25 \text{ }^{\circ}\text{C}$	[1]	-	370	mW
			[2]	-	570	mW
			[3]	-	530	mW
			[4]	-	700	mW
			[5]	-	450	mW
			[6]	-	760	mW
			[7]	-	700	mW
			[8]	-	1450	mW

**Per device**

$P_{tot}$	total power dissipation	$T_{amb} \leq 25 \text{ }^{\circ}\text{C}$	[1]	-	510	mW
			[2]	-	780	mW
			[3]	-	730	mW
			[4]	-	960	mW
			[5]	-	620	mW
			[6]	-	1040	mW
			[7]	-	960	mW
			[8]	-	2000	mW
$T_j$	junction temperature			-	150	$^{\circ}\text{C}$
$T_{amb}$	ambient temperature			-55	150	$^{\circ}\text{C}$
$T_{stg}$	storage temperature			-65	150	$^{\circ}\text{C}$

- [1] Device mounted on an FR4 PCB, single-sided 35  $\mu\text{m}$  copper strip line, tin-plated and standard footprint.
- [2] Device mounted on an FR4 PCB, single-sided 35  $\mu\text{m}$  copper strip line, tin-plated, mounting pad for collector 1  $\text{cm}^2$ .
- [3] Device mounted on 4-layer PCB 35  $\mu\text{m}$  copper strip line, tin-plated and standard footprint.
- [4] Device mounted on 4-layer PCB 35  $\mu\text{m}$  copper strip line, tin-plated, mounting pad for collector 1  $\text{cm}^2$ .
- [5] Device mounted on an FR4 PCB, single-sided 70  $\mu\text{m}$  copper strip line, tin-plated and standard footprint.
- [6] Device mounted on an FR4 PCB, single-sided 70  $\mu\text{m}$  copper strip line, tin-plated, mounting pad for collector 1  $\text{cm}^2$ .
- [7] Device mounted on 4-layer PCB 70  $\mu\text{m}$  copper strip line, tin-plated and standard footprint.
- [8] Device mounted on 4-layer PCB 70  $\mu\text{m}$  copper strip line, tin-plated, mounting pad for collector 1  $\text{cm}^2$ .



(1) 4-layer PCB 70  $\mu\text{m}$ , mounting pad for collector 1  $\text{cm}^2$

(2) FR4 PCB 70  $\mu\text{m}$ , mounting pad for collector 1  $\text{cm}^2$

(3) 4-layer PCB 70  $\mu\text{m}$ , standard footprint

(4) 4-layer PCB 35  $\mu\text{m}$ , mounting pad for collector 1  $\text{cm}^2$

(5) FR4 PCB 35  $\mu\text{m}$ , mounting pad for collector 1  $\text{cm}^2$

(6) 4-layer PCB 35  $\mu\text{m}$ , standard footprint

(7) FR4 PCB 70  $\mu\text{m}$ , standard footprint

(8) FR4 PCB 35  $\mu\text{m}$ , standard footprint

Fig. 1. Per transistor: power derating curves

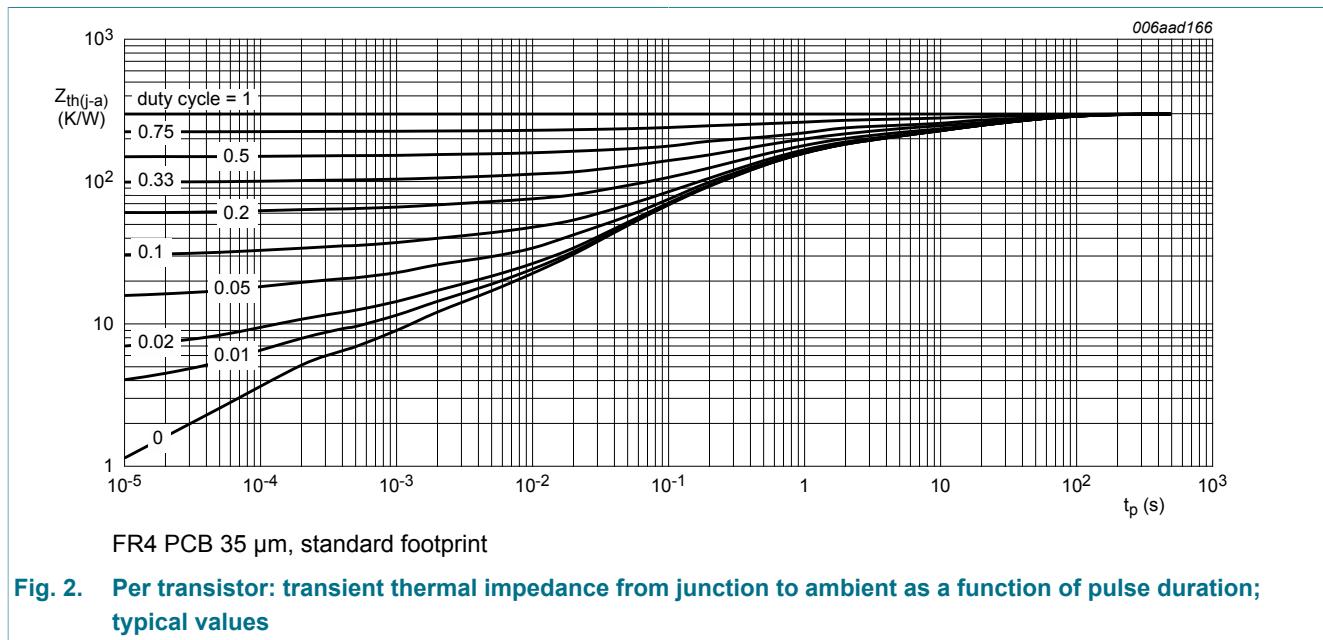
## 9. Thermal characteristics

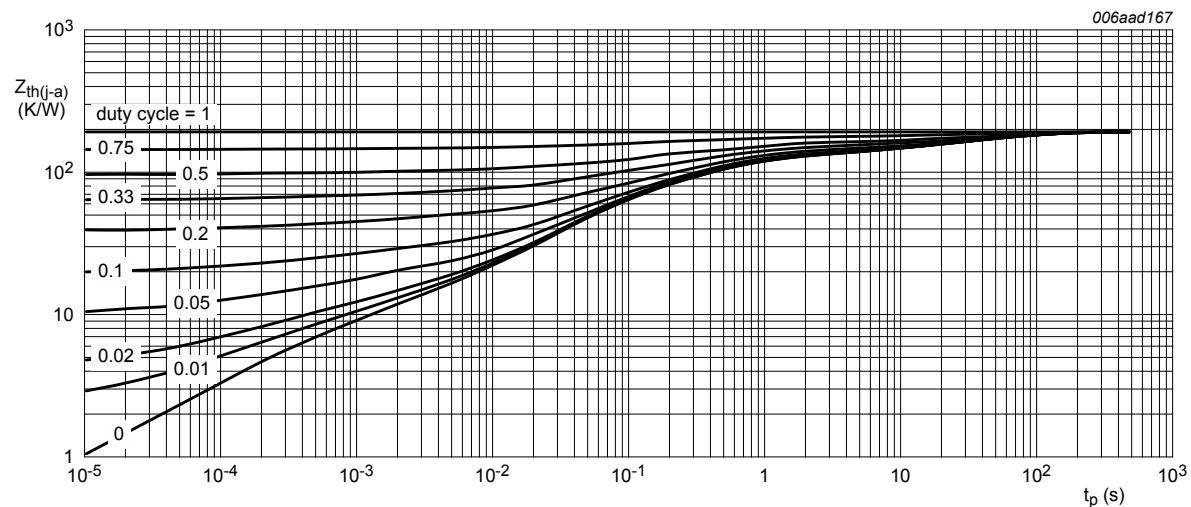
Table 6. Thermal characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
<b>Per transistor</b>						
$R_{\text{th(j-a)}}$	thermal resistance from junction to ambient	in free air	[1]	-	-	338 K/W
			[2]	-	-	219 K/W
			[3]	-	-	236 K/W
			[4]	-	-	179 K/W
			[5]	-	-	278 K/W
			[6]	-	-	164 K/W
			[7]	-	-	179 K/W
			[8]	-	-	86 K/W
$R_{\text{th(j-sp)}}$	thermal resistance from junction to solder point			-	-	30 K/W

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
<b>Per device</b>							
$R_{th(j-a)}$	thermal resistance from junction to ambient	in free air		[1]	-	-	245 K/W

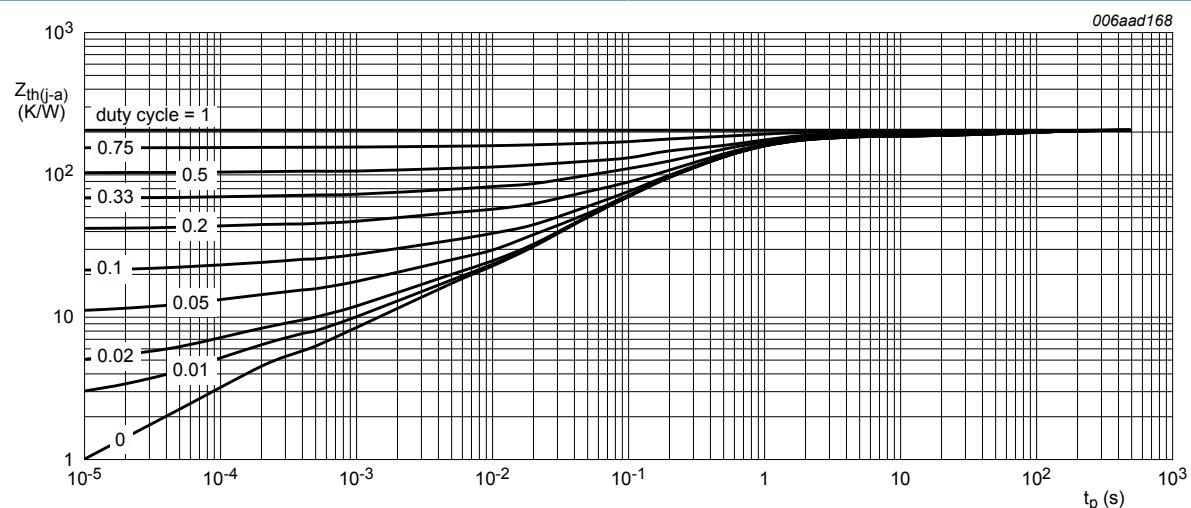
- [1] Device mounted on an FR4 PCB, single-sided 35  $\mu\text{m}$  copper strip line, tin-plated and standard footprint.
- [2] Device mounted on an FR4 PCB, single-sided 35  $\mu\text{m}$  copper strip line, tin-plated, mounting pad for collector 1  $\text{cm}^2$ .
- [3] Device mounted on 4-layer PCB 35  $\mu\text{m}$  copper strip line, tin-plated and standard footprint.
- [4] Device mounted on 4-layer PCB 35  $\mu\text{m}$  copper strip line, tin-plated, mounting pad for collector 1  $\text{cm}^2$ .
- [5] Device mounted on an FR4 PCB, single-sided 70  $\mu\text{m}$  copper strip line, tin-plated and standard footprint.
- [6] Device mounted on an FR4 PCB, single-sided 70  $\mu\text{m}$  copper strip line, tin-plated, mounting pad for collector 1  $\text{cm}^2$ .
- [7] Device mounted on 4-layer PCB 70  $\mu\text{m}$  copper strip line, tin-plated and standard footprint.
- [8] Device mounted on 4-layer PCB 70  $\mu\text{m}$  copper strip line, tin-plated, mounting pad for collector 1  $\text{cm}^2$ .





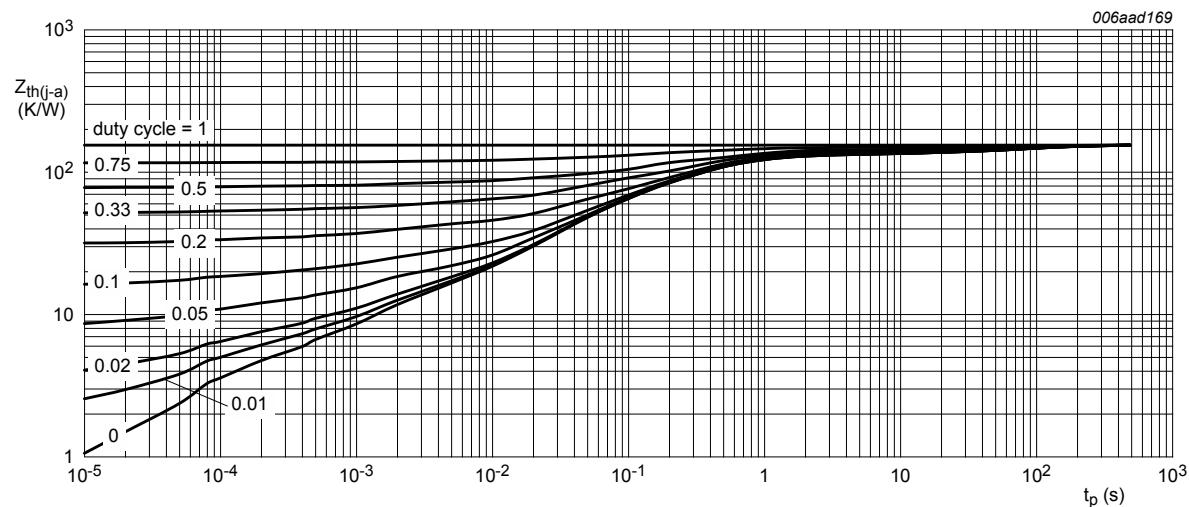
FR4 PCB 35  $\mu$ m, mounting pad for collector 1  $\text{cm}^2$

**Fig. 3. Per transistor: transient thermal impedance from junction to ambient as a function of pulse duration; typical values**



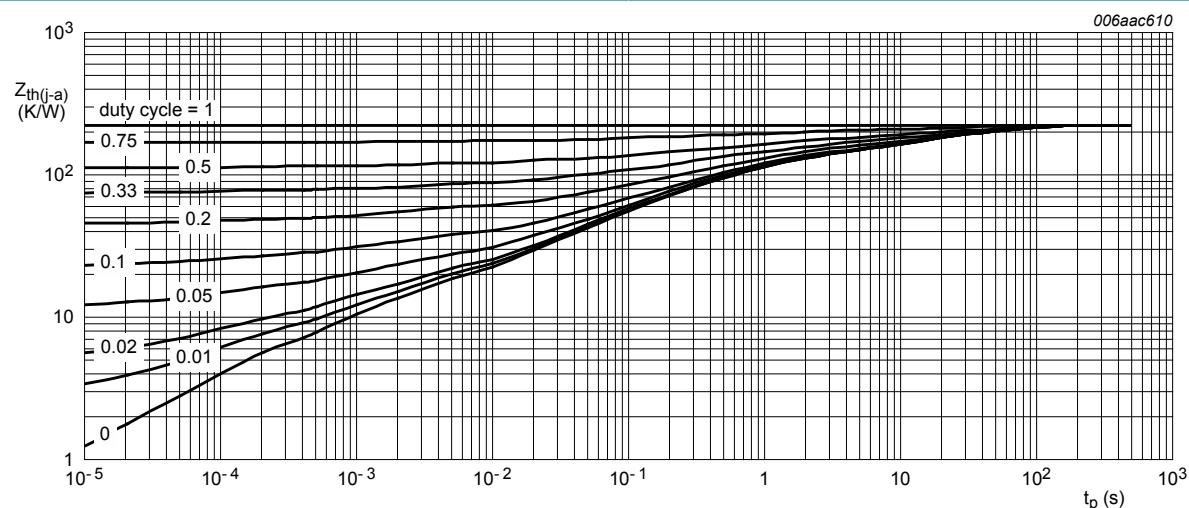
4-layer PCB 35  $\mu$ m, standard footprint

**Fig. 4. Per transistor: transient thermal impedance from junction to ambient as a function of pulse duration; typical values**



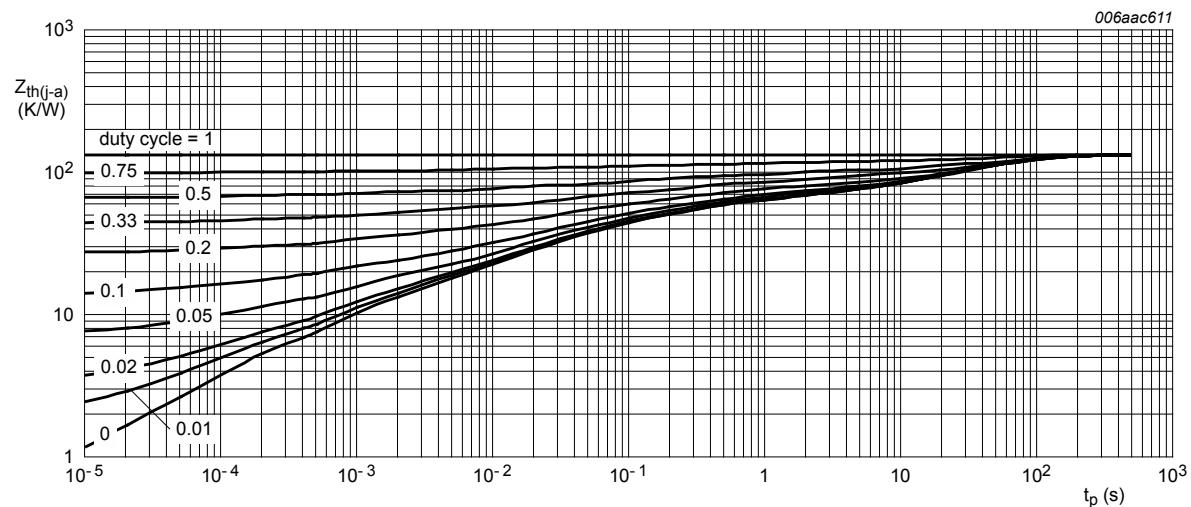
4-layer PCB 35  $\mu\text{m}$ , mounting pad for collector 1  $\text{cm}^2$

**Fig. 5. Per transistor: transient thermal impedance from junction to ambient as a function of pulse duration; typical values**

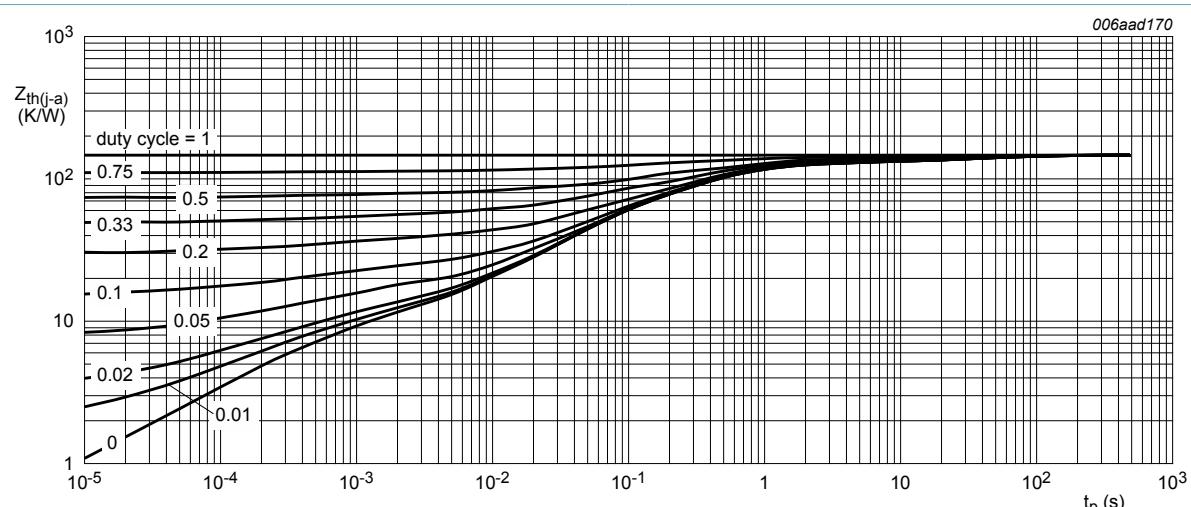


FR4 PCB 70  $\mu\text{m}$ , standard footprint

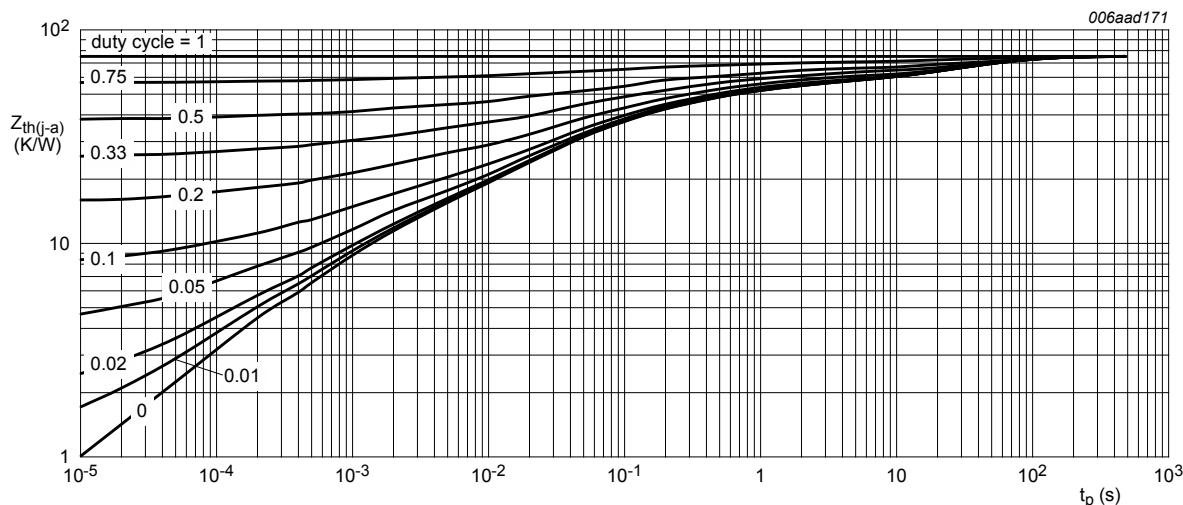
**Fig. 6. Per transistor: transient thermal impedance from junction to ambient as a function of pulse duration; typical values**



**Fig. 7. Per transistor: transient thermal impedance from junction to ambient as a function of pulse duration; typical values**



**Fig. 8. Per transistor: transient thermal impedance from junction to ambient as a function of pulse duration; typical values**



4-layer PCB 70  $\mu\text{m}$ , mounting pad for collector 1  $\text{cm}^2$

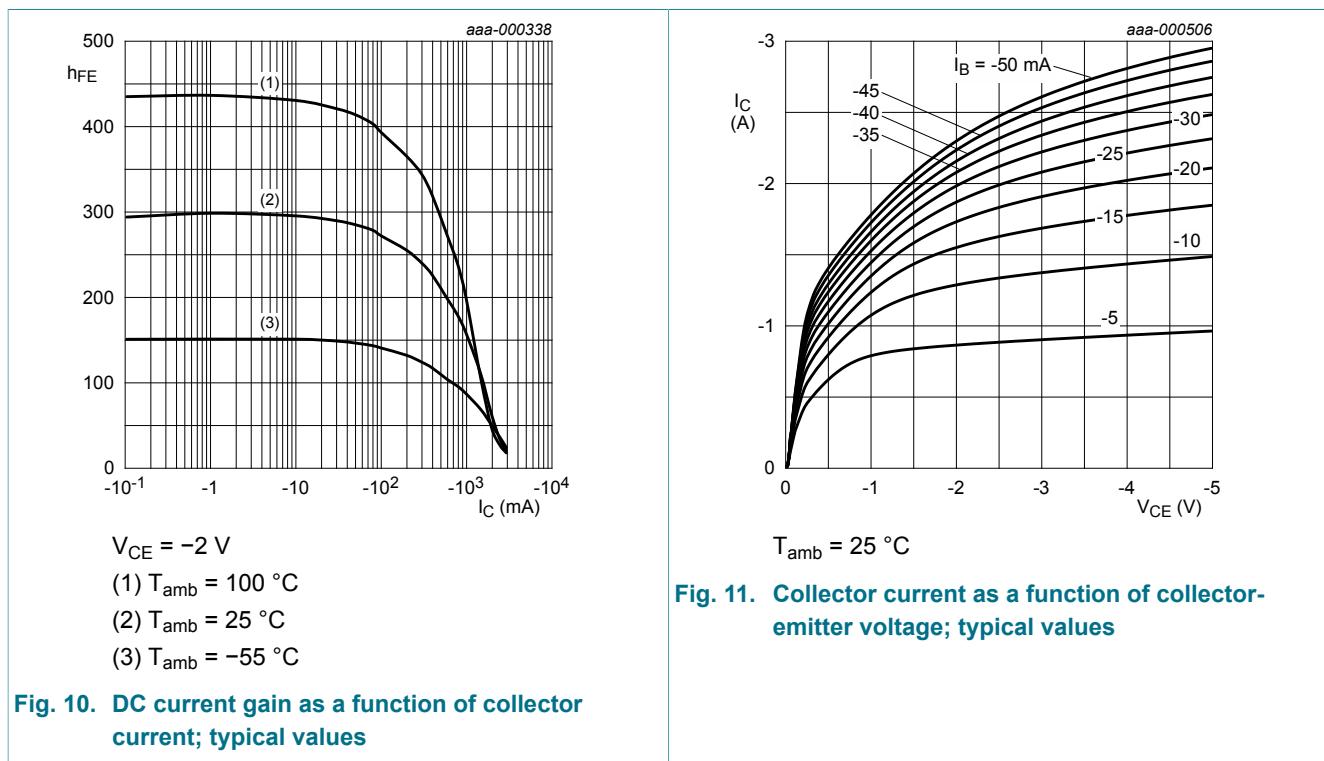
**Fig. 9. Per transistor: transient thermal impedance from junction to ambient as a function of pulse duration; typical values**

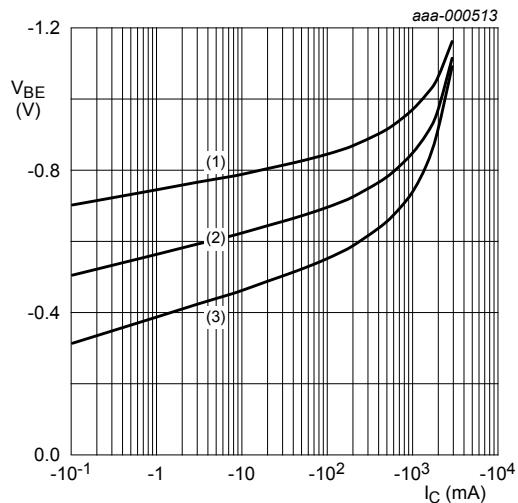
## 10. Characteristics

**Table 7. Characteristics**

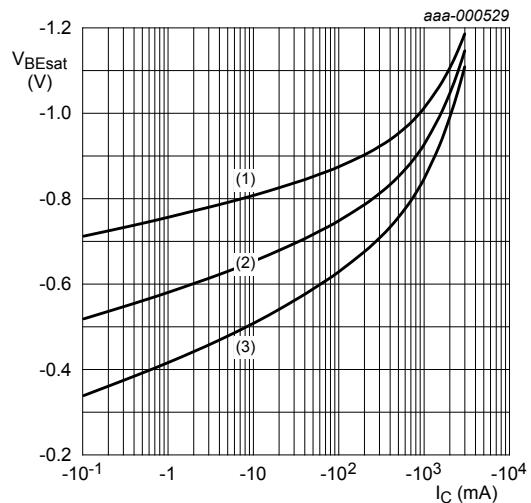
Symbol	Parameter	Conditions	Min	Typ	Max	Unit
<b>Per transistor</b>						
I <sub>CBO</sub>	collector-base cut-off current	V <sub>CB</sub> = -48 V; I <sub>E</sub> = 0 A; T <sub>amb</sub> = 25 °C	-	-	-100	nA
		V <sub>CB</sub> = -48 V; I <sub>E</sub> = 0 A; T <sub>j</sub> = 150 °C	-	-	-50	μA
I <sub>EBO</sub>	emitter-base cut-off current	V <sub>EB</sub> = -5 V; I <sub>C</sub> = 0 A; T <sub>amb</sub> = 25 °C	-	-	-100	nA
h <sub>FE</sub>	DC current gain	V <sub>CE</sub> = -2 V; I <sub>C</sub> = -100 mA; pulsed; t <sub>p</sub> ≤ 300 μs; δ ≤ 0.02 ; T <sub>amb</sub> = 25 °C	170	250	-	
		V <sub>CE</sub> = -2 V; I <sub>C</sub> = -500 mA; pulsed; t <sub>p</sub> ≤ 300 μs; δ ≤ 0.02 ; T <sub>amb</sub> = 25 °C	140	200	-	
		V <sub>CE</sub> = -2 V; I <sub>C</sub> = -1 A; pulsed; t <sub>p</sub> ≤ 300 μs; δ ≤ 0.02 ; T <sub>amb</sub> = 25 °C	110	155	-	
		V <sub>CE</sub> = -2 V; I <sub>C</sub> = -2 A; pulsed; t <sub>p</sub> ≤ 300 μs; δ ≤ 0.02 ; T <sub>amb</sub> = 25 °C	50	75	-	
V <sub>CEsat</sub>	collector-emitter saturation voltage	I <sub>C</sub> = -500 mA; I <sub>B</sub> = -50 mA; pulsed; t <sub>p</sub> ≤ 300 μs; δ ≤ 0.02 ; T <sub>amb</sub> = 25 °C	-	-100	-140	mV
		I <sub>C</sub> = -1 A; I <sub>B</sub> = -50 mA; pulsed; t <sub>p</sub> ≤ 300 μs; δ ≤ 0.02 ; T <sub>amb</sub> = 25 °C	-	-220	-310	mV
		I <sub>C</sub> = -2 A; I <sub>B</sub> = -200 mA; pulsed; t <sub>p</sub> ≤ 300 μs; δ ≤ 0.02 ; T <sub>amb</sub> = 25 °C	-	-365	-500	mV

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
$R_{CEsat}$	collector-emitter saturation resistance	$I_C = -1 \text{ A}; I_B = -100 \text{ mA}; \text{pulsed}; t_p \leq 300 \mu\text{s}; \delta \leq 0.02; T_{amb} = 25^\circ\text{C}$		-	-	250	$\text{m}\Omega$
$V_{BEsat}$	base-emitter saturation voltage	$I_C = -500 \text{ mA}; I_B = -50 \text{ mA}; T_{amb} = 25^\circ\text{C}$		-	-	-1	V
		$I_C = -1 \text{ A}; I_B = -50 \text{ mA}; \text{pulsed}; t_p \leq 300 \mu\text{s}; \delta \leq 0.02; T_{amb} = 25^\circ\text{C}$		-	-	-1	V
		$I_C = -2 \text{ A}; I_B = -200 \text{ mA}; \text{pulsed}; t_p \leq 300 \mu\text{s}; \delta \leq 0.02; T_{amb} = 25^\circ\text{C}$		-	-	-1.2	V
$V_{BEon}$	base-emitter turn-on voltage	$V_{CE} = -2 \text{ V}; I_C = -0.5 \text{ A}; \text{pulsed}; t_p \leq 300 \mu\text{s}; \delta \leq 0.02; T_{amb} = 25^\circ\text{C}$		-	-	-0.9	V
$t_d$	delay time	$V_{CC} = -12.5 \text{ V}; I_C = -1 \text{ A}; I_{Bon} = -50 \text{ mA}; I_{Boff} = 50 \text{ mA}; T_{amb} = 25^\circ\text{C}$		-	10	-	ns
$t_r$	rise time			-	80	-	ns
$t_{on}$	turn-on time			-	90	-	ns
$t_s$	storage time			-	195	-	ns
$t_f$	fall time			-	75	-	ns
$t_{off}$	turn-off time			-	270	-	ns
$f_T$	transition frequency	$V_{CE} = -10 \text{ V}; I_C = -50 \text{ mA}; f = 100 \text{ MHz}; T_{amb} = 25^\circ\text{C}$		50	100	-	MHz
$C_c$	collector capacitance	$V_{CB} = -10 \text{ V}; I_E = 0 \text{ A}; i_e = 0 \text{ A}; f = 1 \text{ MHz}; T_{amb} = 25^\circ\text{C}$		-	16	21	pF

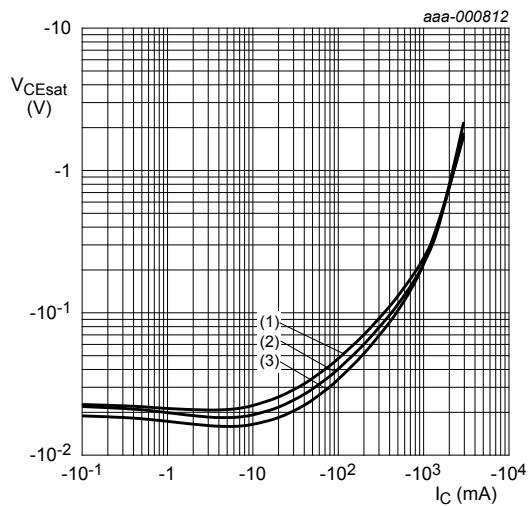




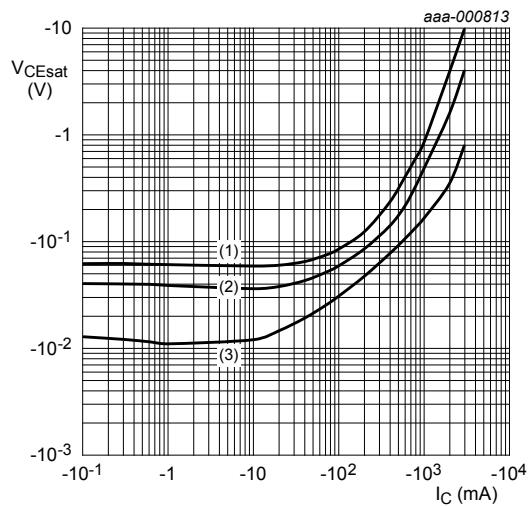
**Fig. 12. Base-emitter voltage as a function of collector current; typical values**



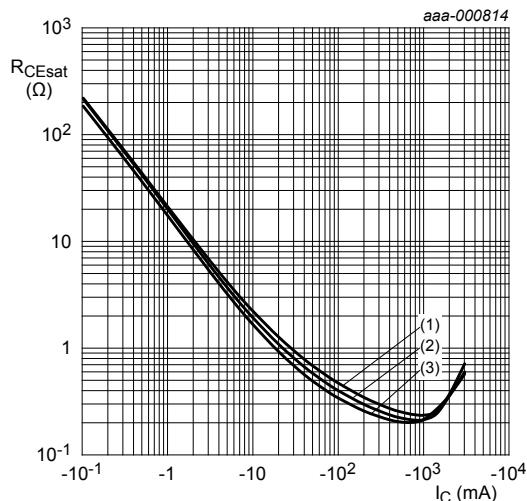
**Fig. 13. Base-emitter saturation voltage as a function of collector current; typical values**



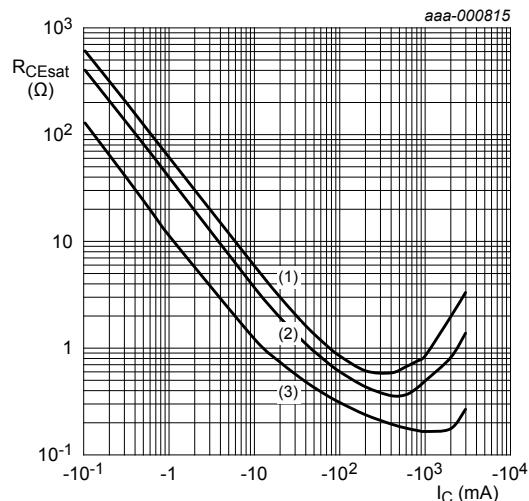
**Fig. 14. Collector-emitter saturation voltage as a function of collector current; typical values**



**Fig. 15. Collector-emitter saturation voltage as a function of collector current; typical values**



**Fig. 16. Collector-emitter saturation resistance as a function of collector current; typical values**



**Fig. 17. Collector-emitter saturation resistance as a function of collector current; typical values**

## 11. Test information

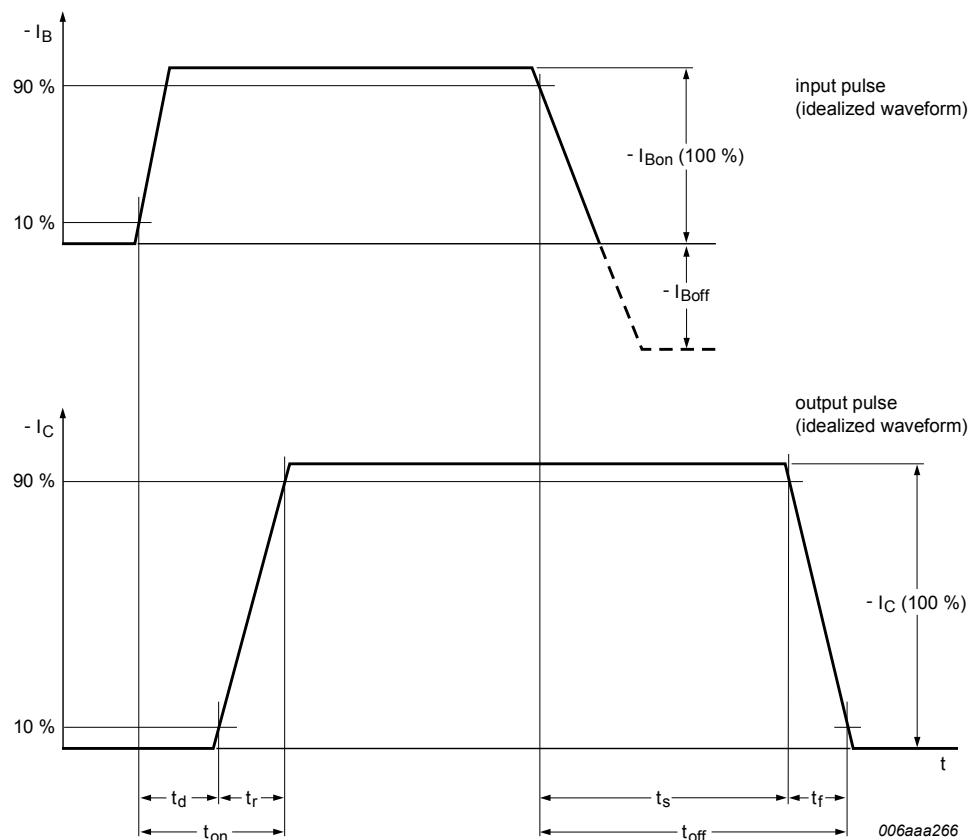


Fig. 18. BISS transistor switching time definition

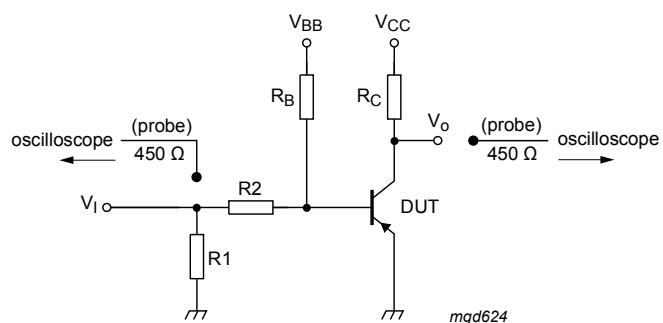


Fig. 19. Test circuit for switching times

### 11.1 Quality information

This product has been qualified in accordance with the Automotive Electronics Council (AEC) standard *Q101 - Stress test qualification for discrete semiconductors*, and is suitable for use in automotive applications.

## 12. Package outline

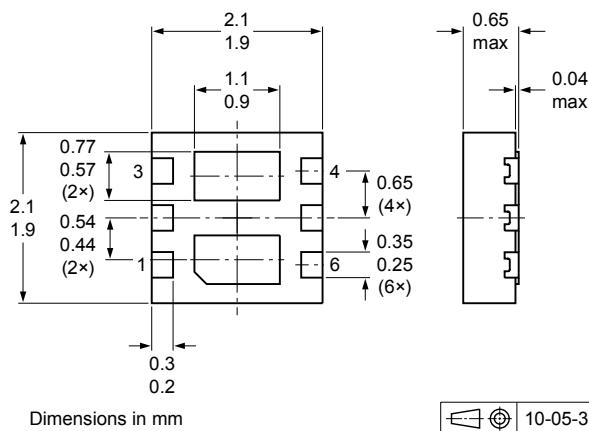


Fig. 20. Package outline DFN2020-6 (SOT1118)

## 13. Soldering

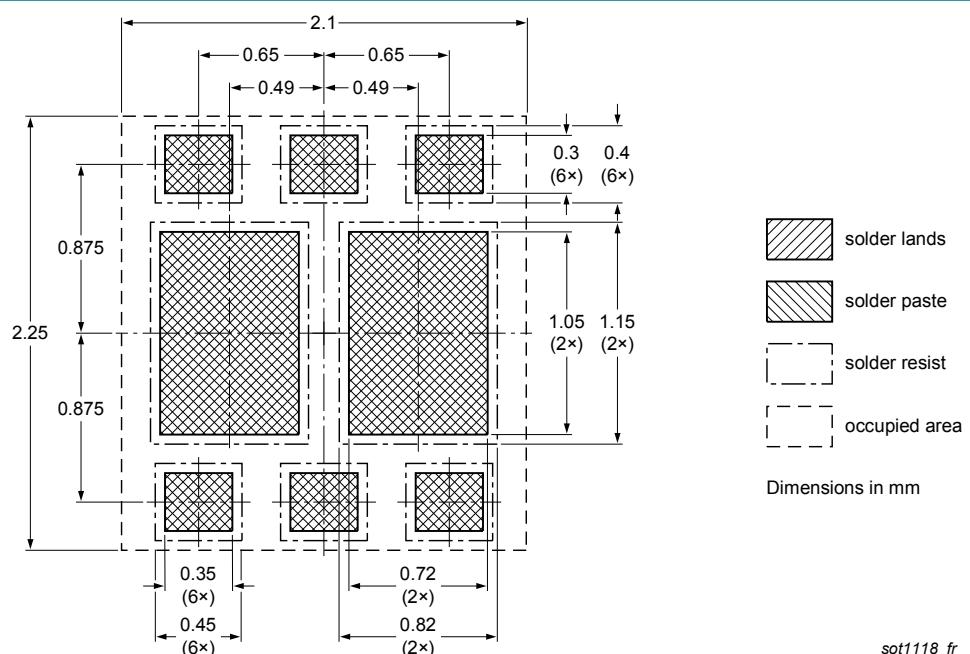


Fig. 21. Reflow soldering footprint for DFN2020-6 (SOT1118)

## 14. Revision history

Table 8. Revision history

Data sheet ID	Release date	Data sheet status	Change notice	Supersedes
PBSS5260PAP v.1	20121212	Product data sheet	-	-

## 15. Legal information

### 15.1 Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

- [1] Please consult the most recently issued document before initiating or completing a design.
- [2] The term 'short data sheet' is explained in section "Definitions".
- [3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URL <http://www.nxp.com>.

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Date of release: 12 December 2012

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